

描述 / Descriptions

GEJ

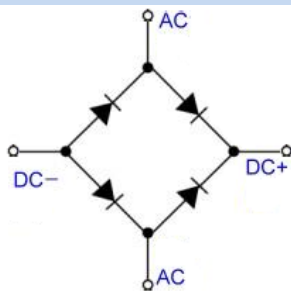
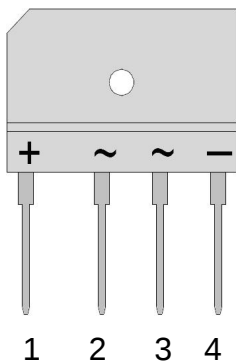
Ultrafast Recovery rectifier bridge in a GBJ Plastic Package.

特征 / Features

Glass passivated process to produce Ultrafast Recovery rectifier bridge ,with low reverse leakage current and high reliability.

用途 / Applications

For high frequency, high voltage, high current rectifier diode, freewheeling diode。

内部等效电路 / Equivalent Circuit**引脚排列 / Pinning**

PIN1 DC+ PIN2 AC PIN 3 AC PIN 4 DC-

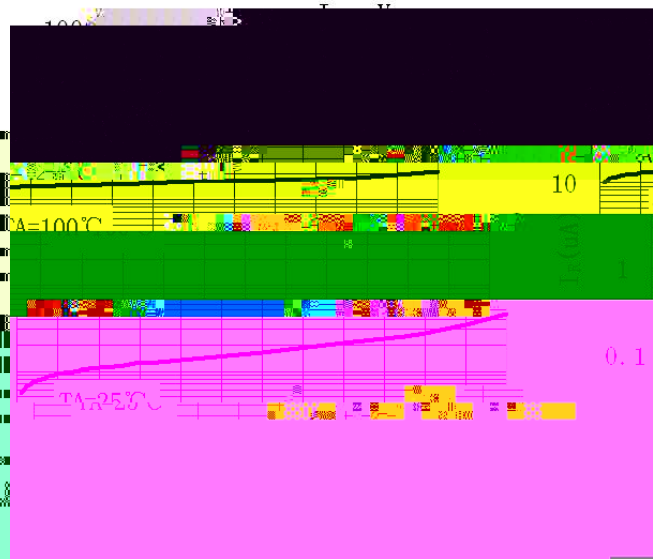
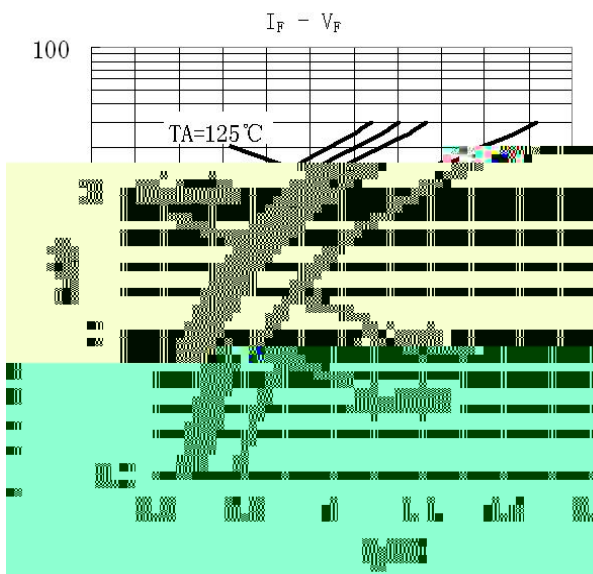
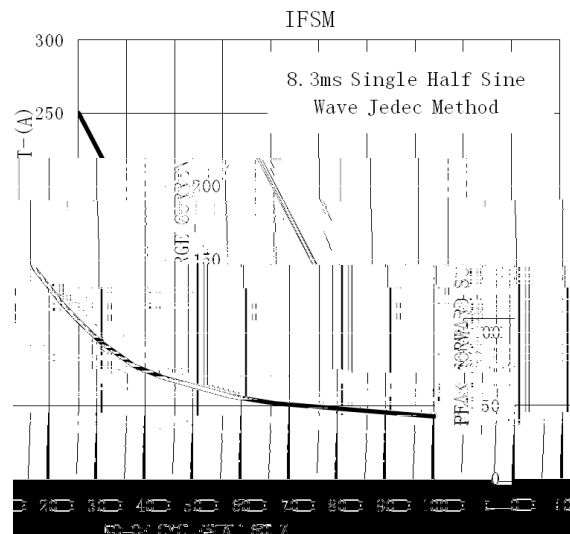
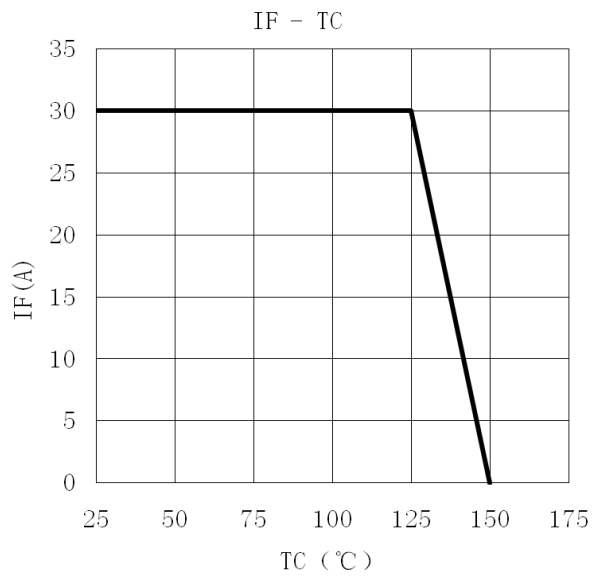
放大及印章代码 / h_{FE} Classifications & Marking

See Marking Instructions

Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	600	V
Maximum RMS Voltage	V_{RMS}	420	V
Maximum DC Blocking Voltage	V_{DC}	600	V
Maximum Average Forward Current	$I_{(AV)}$	4×30	A
Peak forward surge current	I_{FSM}	250	A
Typical Thermal Resistance Junction to Case	$R_{\theta JC}$	0.6	/W
Junction Temperature Range	T_J	150	
Storage Temperature Range	T_{stg}	-55~150	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse Voltage	V_R	$I_R=1mA$	600	680		V
Forward Voltage	V_F	$I_F=5A \quad T_C=25^\circ C$		1.32	1.45	V
		$I_F=5A \quad T_C=125^\circ C$		0.90	1.25	
		$I_F=15A \quad T_C=25^\circ C$		1.90	2.25	
		$I_F=15A \quad T_C=125^\circ C$		1.26	1.65	
		$I_F=30A \quad T_C=25^\circ C$		2.35	2.65	
		$I_F=30A \quad T_C=125^\circ C$		1.65	2.15	
Instantaneous Reverse Current	I_R (Note 1)	$V_R=600V \quad T_a=25^\circ C$			10	μA
		$V_R=600V \quad T_a=125^\circ C$			500	
Reverse Recovery Time	t_{rr}	$I_F=0.5A \quad I_R=1.0A$ $I_{RR}=0.25A$		40	50	ns

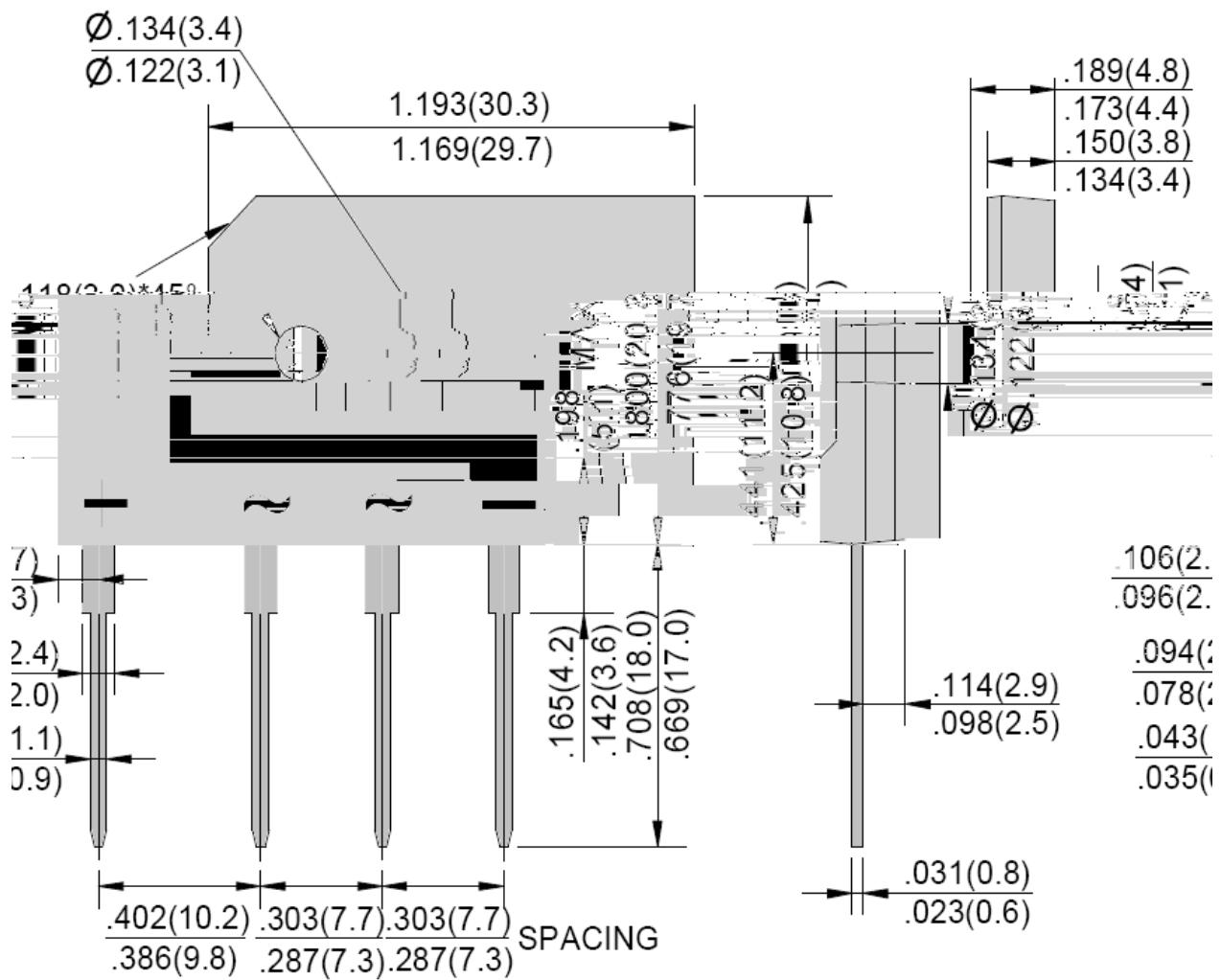
电参数曲线图 / Electrical Characteristic Curve



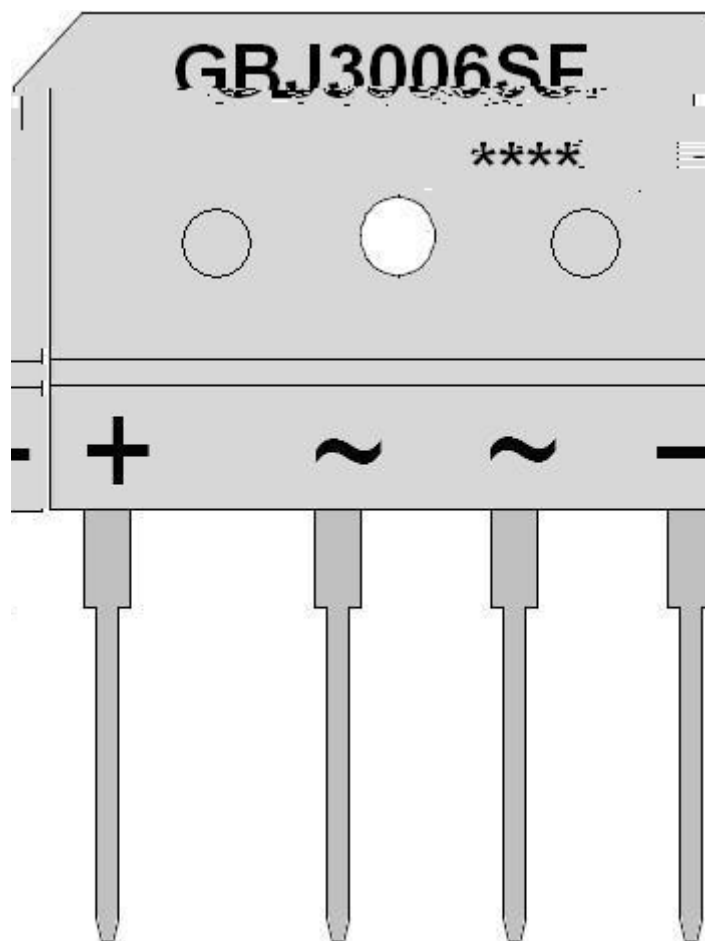


外形尺寸图 / Package Dimensions

GBJ



印章说明 / Marking Instructions



GBJ3006SF

+ DF -

Note:

GBJ3006SF

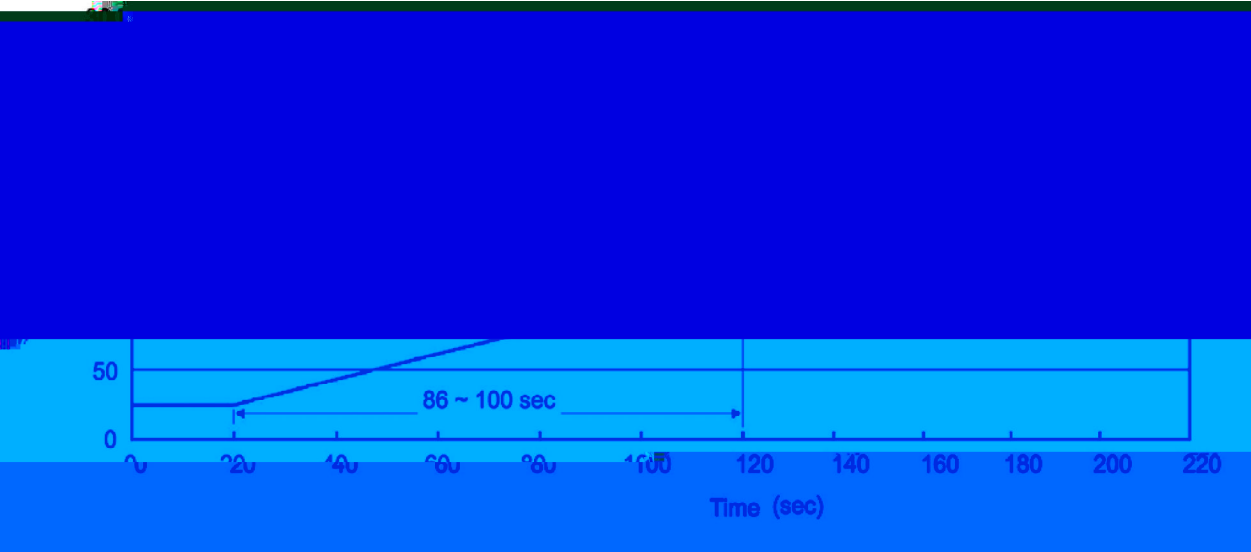
Product Type

Lot No. Code, code change with Lot No.

+ DF -

Piq fxqcwlrq

波峰焊温度曲线图(无铅) / Temperature Profile for Dip Soldering(Pb-Free)



- Note:

1

25 150

60 90sec;

1.Preheating:25~150 , Time:60~90sec.

2

255±5

5±0.5sec;

2.Peak Temp.:255±5 , Duration:5±0.5sec.

3

2 10 /sec.

3. Cooling Speed: 2~10 /sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

270±5

10±1 sec.

Temp.:270±5

Time:10±1 sec

包装规格 / Packaging SPEC.

/ PLUG				/ TUBE			
Packaging	Units/Tube	Units/Box	Dimension	Packaging	Units/Tube	Units/Box	Dimension
3	100	1000	15.2x7.6x1.27	3	50	500	15.2x7.6x1.27

使用说明 / Notices